

Customer No.: 31561
Application No: 10/710,786
Docket No.: 11577-US-PA

AMENDMENTS

To the Claims

1. (currently amended) A bumping process, comprising:
providing a wafer having a plurality of bonding pads and a passivation layer that exposes the bonding pads;
forming a metallic layer over the bonding pad wafer to cover at least the bonding pads,
wherein a portion of the passivation layer is exposed by the metallic layer;
forming a first photoresist layer over the wafer;
forming a second photoresist layer over the first photoresist layer, wherein the first photoresist layer has a viscosity smaller than the second photoresist layer;
performing an exposure and development process to form a plurality of openings in the first and the second photoresist layer, wherein the openings expose the metallic layer;
filling a solder material into the openings to form a plurality of solder posts; and
removing the first photoresist layer and the second photoresist layer.
2. (original) The bumping process of claim 1, further comprising performing a reflow process to transform the solder posts into a plurality of bumps over the metallic layer after removing the first and the second photoresist layer.
3. (original) The bumping process of claim 1, wherein the first photoresist layer comprises a dry film.
4. (original) The bumping process of claim 1, wherein the second photoresist layer comprises a dry film.

Customer No.: 31561
Application No: 10/710,786
Docket No.: 11577-US-PA

5. (original) The bumping process of claim 1, wherein the step of filling the solder material into the openings comprises electroplating or stencil printing.

6. (currently amended) A method for enhancing the adhesion between a photoresist material and a substrate, comprising:

forming a first photoresist layer over the substrate, wherein a top surface of the substrate comprises a first exposed portion of a metallic layer and a second exposed portion of a material layer around the metallic layer with a non-smooth flat surface; and

forming a second photoresist layer over the first photoresist layer, wherein the second photoresist layer has a higher viscosity than the first photoresist layer.

7. (original) The method of claim 6, wherein the first photoresist layer comprises a dry film.

8. (original) The method of claim 6, wherein the second photoresist layer comprises a dry film.